

Draft dated 1 March 2006

PRELIMINARY MEETING AGENDA – CE-2.9 SUBCOMMITTEE ON SOCKETS 24 – 29 April 2006, FT. LAUDERDALE, FL

1. Approval of the 17 – 18 October 2005 Minutes

"If any SP listed below receives insufficient votes for approval, the committee may approve the document for EDEC ballot at this meeting. It is the responsibility of the member to submit comments in writing prior to the meeting".

2. SPECIFICATIONS BY PROJECT NUMBER

- A. SP-4965: Rev. EIA-540B0AE: Detail Land Grid Array (Contech Research)
To be superseded by EIA-364-1003, Ball Grid Array (BGA) and Land Grid Array (LGA) Test Sequence for Electrical Connectors and Sockets, when published.
- B. SP-4970: EIA-540DAAA-A: Detail, DIP
Sent to EIA to process the EDEC ballot on 6 October 2005.
- C. SP-4971: EIA-700A0AB: 68-pin Memory Card Connector
Sent to EIA to process the EDEC ballot on 6 October 2005.
- D. SP-4973: EIA-540B0AB: Low Pin Count BGA (Contech Research)
To be superseded by EIA-364-1003, Ball Grid Array (BGA) and Land Grid Array (LGA) Test Sequence for Electrical Connectors and Sockets, when published.
- E. SP-4982-1: EIA-5400000A: Generic
Sent letter to EIA (mccwil244) for EDEC ballot for reaffirmation on 26 January 2006.
- F. SP-4983: EIA-540BAAA-A: Detail, Mechanically Actuated PGA (Contech Research)
Sent letter to cancel the project to EIA on 17 September 2005.
- G. SP-5055: Replacement document for EIA-676 Detail, SFF 1.8 inch (45.7 mm) Disk Drives
Need to verify final ballot count.
- H. SP-5056: EIA-674: Detail, SFF 1.8" Disk Drives
Sent to EIA for EDEC ballot on 10 October 2005.
- I. SP-5058-A: EIA-720: Detail, SFF 2.5" Disk Drives
Sent specification and letter (mccwil248) to EIA for a second SP ballot on 1 February 2006.

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J. SP-5059: EIA-677: Detail, SFF Power Connector Pin Dimensions

Sent letter to EIA for EDEC ballot to reaffirm the specification on 11 October 2005.

K. SP-5112 as follows:

- EIA-700A0AC: Detail, 88-pin DRAM Connector
- EIA-540A000-A: Sectional, Chip Carrier Sockets
- EIA-540AA00: Blank, Leadless Chip Carrier Sockets
- EIA-540AAAA: Detail, Type A Chip Carrier Sockets
- EIA-540AB00: Blank, PQFP
- EIA-540ABAA: Detail, PQFP
- EIA-540AC00: Blank, PCC
- EIA-540ACAA: Detail, PCC
- EIA-540AD00: Blank, Adaptor QFP to PGA
- EIA-540B000: Sectional, PGA
- EIA-540BA00: Blank, PGA
- EIA-540BAAB: Detail, Non-Mechanical PGA
- EIA-540BAAC: Detail, Flex Carrier PGA
- EIA-540D000-A: Sectional, In-Line Packages
- EIA-540DA00: Blank, DIP (Will be sent out for review)
- EIA-540DAAB: Detail, Flex Carrier DIP
- EIA-540EA00: Blank, Round Sockets
- EIA-540EAAA: Detail, Round Sockets
- EIA-540F000: Sectional, Multi-Package Modules

EIA final ballot count as of 14 February 2006 is as follows: 5 approvals, 2 abstentions and 1 unfavorable from Max Peel. Max returned his postcard and still disapproves.

L. SP-5114 as follows:

- 540C000: Sectional Relay Sockets
- 540CA00: Blank, Relay Sockets
- 540CAAA: Detail, 10A Relay Socket
- 540CAAB: Detail, 5A Relay Socket

EIA final ballot count as of 14 February 2006 is as follows: 6 approvals, 2 abstentions and 1 unfavorable from Max Peel. Max returned his postcard and still disapproves.

3. SPECIFICATIONS AWAITING PROJECT NUMBERS

A. EIA-364-1003, Ball Grid Array (BGA) and Land Grid Array (LGA) Test Sequence for Electrical Connectors and Sockets (Contech Research, Tom Peel)

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4. NEW BUSINESS

Prepared by
Carl Fritz, Facilitator CE-2.9